



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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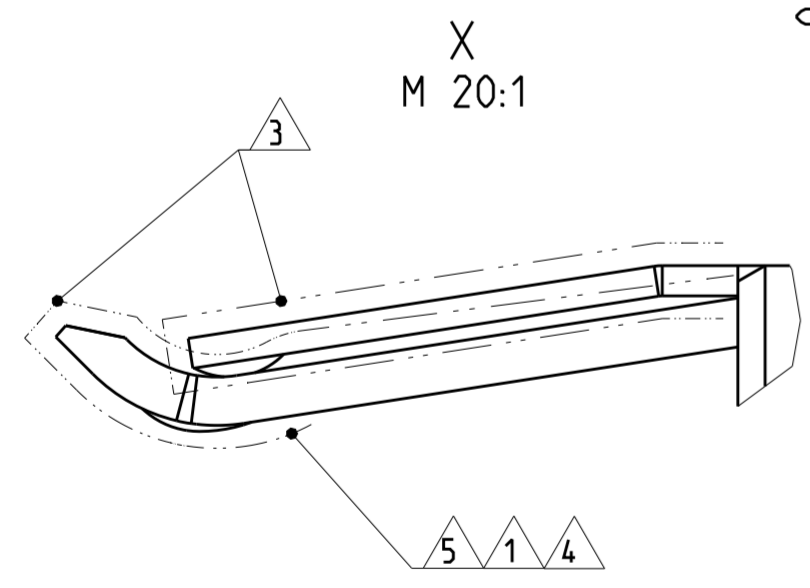
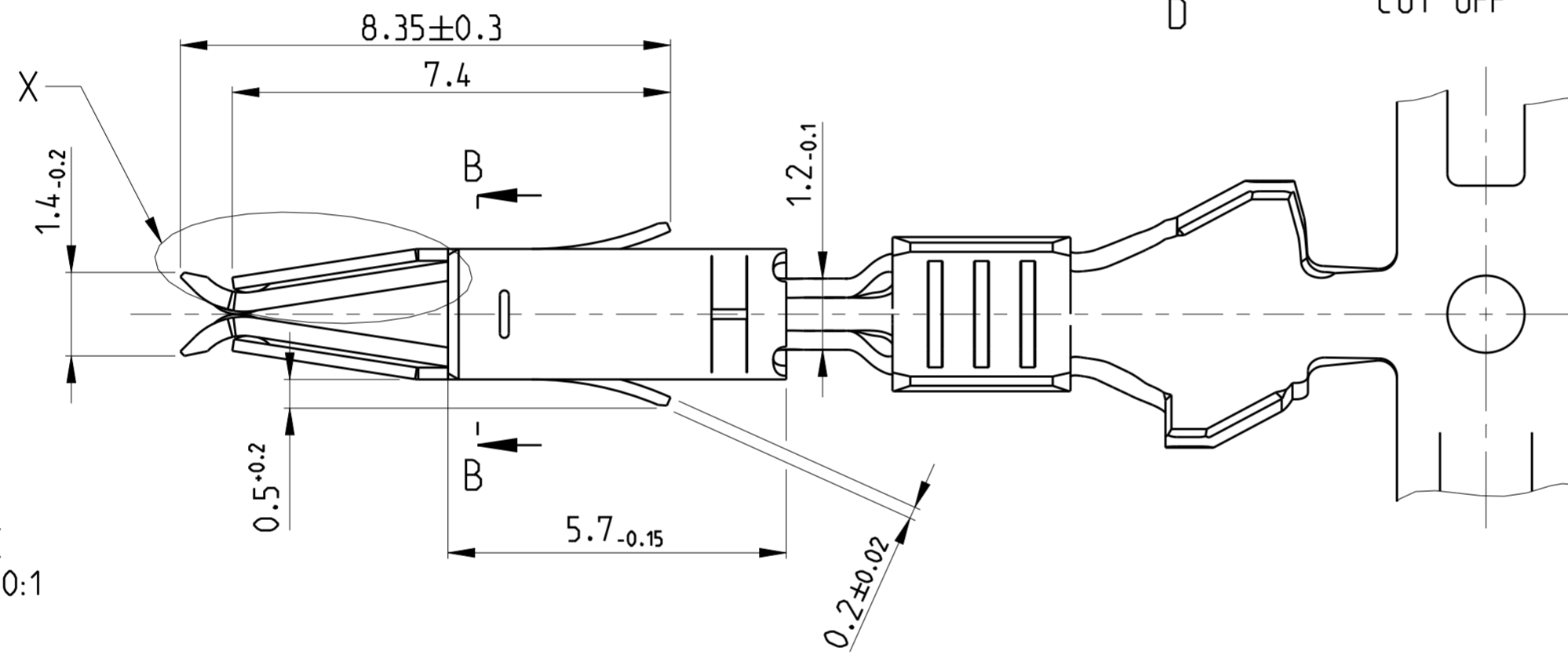
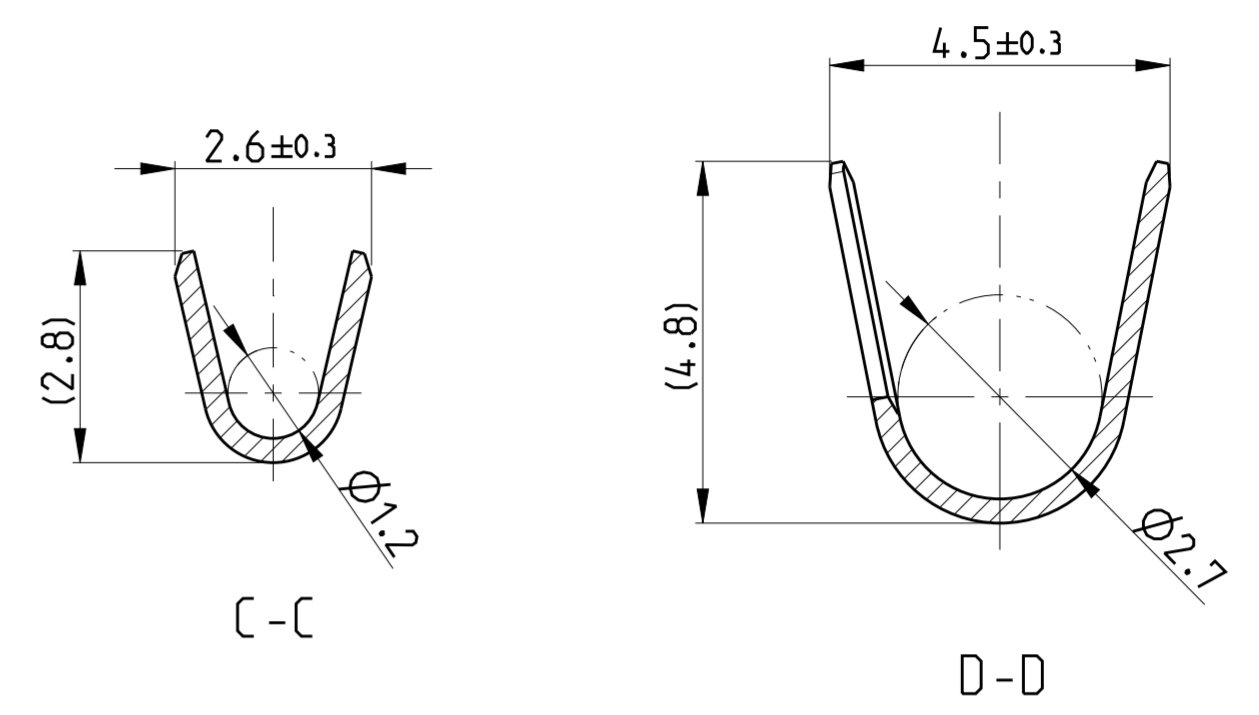
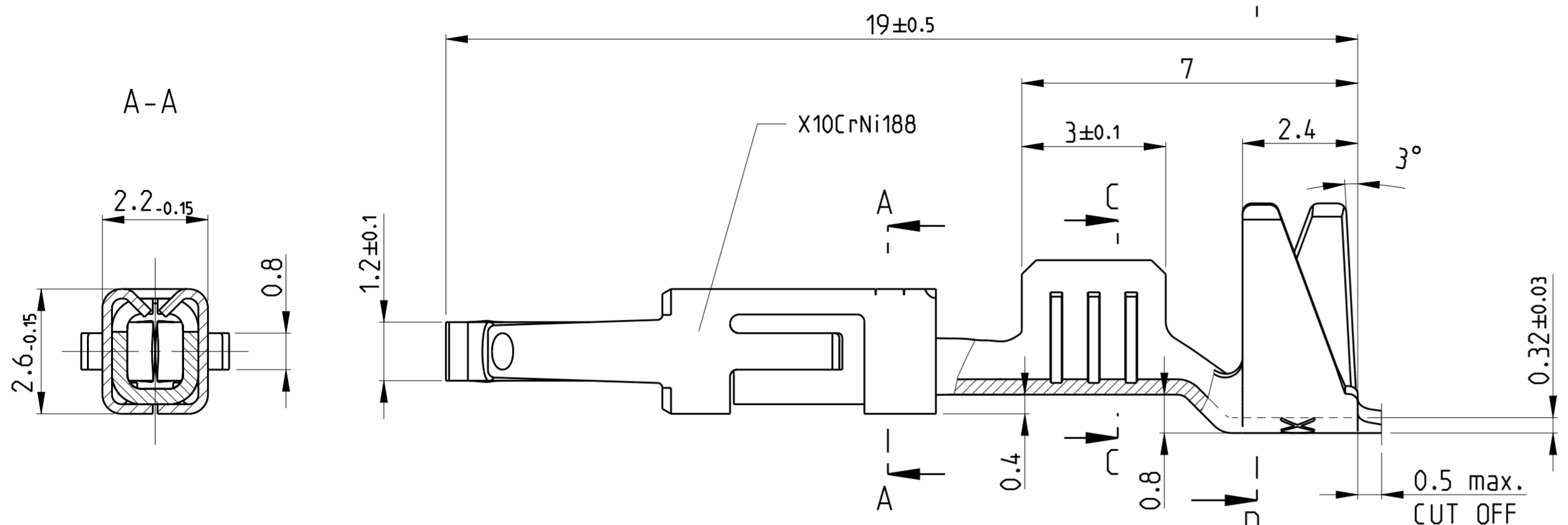
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



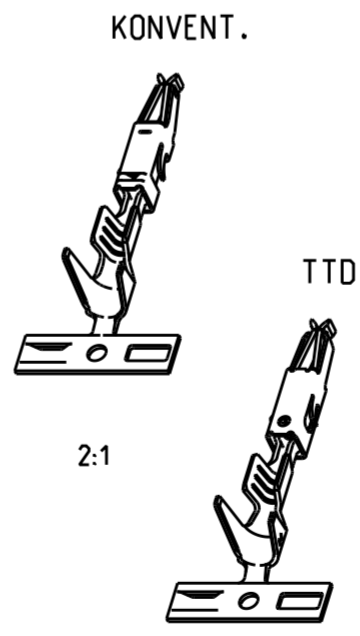
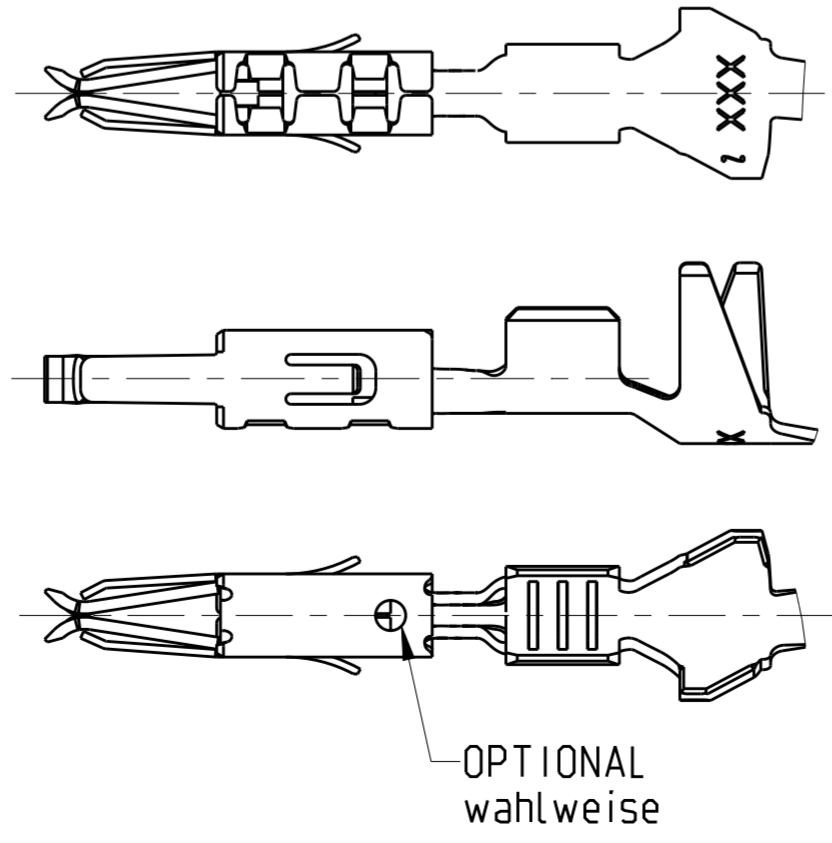
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LOC	DIST	REVISIONS					
		P	LTR	DESCRIPTION	DATE	DWN	APVD
A1	-	N3		NEW VERISON OF GOLD CONTACTS PRERMITTED.	18MAY2011	Kirs	Mair
		N4		OPTIONAL to note 8 TTD added. (area A3)	29JUN2011	Kirs	Mair
		N5		PRODUCT SPEC CORRECTED	23JUN2014	Ho.	Eder
		N6		ECR-15-012070	13AUG2015	JB.JH	BK

7 KONVENTIONELL



8 TWO TRACK DIE
M 5:1



- 1 SELECTIVE GOLD PLATED MIN. 0.8 µm OVER NI
selektiv vergoldet 0.8 µm ueber Ni
- 2 TIN PLATED MIN. 0.2 µm OVER NI
verzinkt 0.2 µm ueber Ni
- 3 CONTACT SURFACE SEL. GOLD PLATED MIN. 0.8 µm OVER NI
CANTILEVER SPRING COMPLETELY GOLD PLATED ON BOTH SIDES
sel. vergoldet auf der Kontaktobenseite 0.8 µm min. ueber Ni
Ueberfeder komplett auf beiden Seiten vergoldet
- 4 GAL. TIN PLATED MIN. 1.0 µm OVER NI
gal. verzinkt 1.0 µm ueber Ni
- 5 SELECTIVE GOLD PLATED MIN. 1.27 µm OVER NI
selektiv vergoldet 1.27 µm min. ueber Ni
- 6 WIRE RANGE : 0.5 - 1.0 mm²
INSULATION-Ø: 2.8 mm (SINGLE WIRE SEAL)
Drahtgroessenbereich: 0.5 - 1.0 mm²
Isolations-Ø: 2.8 mm (Einzeldichtung)

VERSION	SURFACE / Oberflaeche	MATERIAL	PART NO	REV
8 7	5 2	CuFe2	962876-7	B
8 7	3 4 2	CuSn4	962876-6	N
8 7	1 2	CuFe2	962876-5	N
8 7	1 2	CuSn4	962876-3	N
8	PRETIN / vorverzinkt	CuFe2	962876-2	N
8	PRETIN / vorverzinkt	CuSn4	962876-1	N

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS: mm	TOLERANCES UNLESS OTHERWISE SPECIFIED:	DWN R.Hofer 05-JAN-89	CHK L.Nix 05-APR-89	APVD M.Bleicher 25-JUN-08
0-PLC ±0.2	1-PLC ±0.2	2-PLC ±0.2	3-PLC ±0.2	4-PLC ±0.2
ANGLES ±2°	FINISH	PRODUCT SPEC 108-18055	APPLICATION SPEC 114-18081	WEIGHT 0.3 g
MATERIAL		Customer Drawing	SCALE 10:1	SHEET 1 OF 1

STE TE Connectivity

MICRO TIMER 2 CONTACT WITH DOUBLE LOCKING LANCE mit doppelter Rastfeder

SIZE A2 CAGE CODE 00779 DRAWING NO. C-962876 RESTRICTED TO -

REV N6